

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hong XIAO	06/19/2008
RECEIVING PARTY DATA	
Name:	Material Sciences Corporation
Street Address:	2200 East Pratt Boulevard
City:	Elk Grove Village
State/Country:	ILLINOIS
Postal Code:	60007
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12137024
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	6666.170
NAME OF SUBMITTER:	Joseph W. Berenato, 30546
Total Attachments: 2 source=ASSIGN#page1.tif source=ASSIGN#page2.tif	

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REEL: 021119 FRAME: 0231

ASSIGNMENT


In consideration for One Dollar and other good and valuable consideration, receipt of which is hereby acknowledged, I, Hong Xiao, of 25511 Ranchwood Drive, Farmington Hills, Michigan 48335, USA, hereby sell, assign, transfer and set over to Material Sciences Corporation, having its principal place of business at 2200 East Pratt Boulevard, Elk Grove Village, Illinois 60007, USA, its successors, assigns, nominees, or other legal representatives, the entire right, title and interest in all countries including the priority rights derived from the hereinafter designated application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International Convention, in and to the invention or inventions made by me for **CONSTRAINED LAYER DAMPER, AND RELATED METHODS**, and the application for Letters Patent of the United States therefor, executed by me on or about June 9, 2008, and bearing a filing date of June 11, 2008, and a Serial No. 12/137,024 together with all rights, including the sole rights under the aforesaid International Convention to apply for and obtain Letters Patent for said invention or inventions in the United States and in all other countries of the world, including original, divisional, continuation, continuation-in-part, reissue, utility and design patents, patents of addition, confirmation patents, registration patents, petty patents, utility models, etc., and all other types of patents and the like, and all renewals and extensions of any of them, and the entire right, title and interest in and to all such Letters Patent, the applications therefor and the subject matter of all claims obtained in said Letters Patent, and authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue Letters Patent on applications as aforesaid to issue the said Letters Patent to the Material Sciences Corporation, its

successors, assigns, nominees or other legal representatives, as assignee of the entire interest, and covenant that I convey the entire interest herein assigned and that I have not executed and will not execute any agreement in conflict herewith.

I further covenant and agree that whenever requested by said Material Sciences Corporation, its successors, assigns, nominees or legal representatives, I will execute and deliver or cause to be executed and delivered such further patent applications, assignments, oaths, disclaimers and other documents, give or cause to be given such evidence and furnish or cause to be furnished such information within my knowledge or control, and do or cause to be done such other acts and furnish or cause to be furnished such other assistance, as it or any of them may deem necessary or desirable in connection with obtaining and/or maintaining any Letters Patent as aforesaid for said invention or inventions, or in connection with any suit or controversy, including interference proceedings, relating to any of such Letters Patent or to any applications therefor or in order to vest or perfect in it or in any of them or to protect or enforce the right, title and interest herein assigned, or otherwise effectuate the premises, all without further consideration but at the expense of said Material Sciences Corporation, its successors, assigns, nominees or other legal representatives.

I hereby grant to Joseph W. Berenato, III of Berenato, White & Stavish, LLC, full power to insert herein the execution and filing dates and serial number of the application for Letters Patent of the United States first above mentioned.

Date: 6/19/2008



Hong Xiao